

AMENDMENT TRANSMITTAL LETTER

Docket No.
TESSERA 3.0-109 CIP DIV

Application No.
09/776,356

Filing Date
February 2, 2001

Examiner
D. Graybill

Art Unit
2827

Applicant(s): Young-Gon Kim, Belgacem Haba, and Vernon Solberg

Invention: STACKED MICROELECTRONIC ASSEMBLY AND METHOD THEREFOR

TO THE COMMISSIONER FOR PATENTS

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED					
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	33	- 20 =	13	x 18.00	234.00
Independent Claims	4	- 4 =		x	0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					
Other fee (please specify):					
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					234.00

☒ Large Entity

☐ Small Entity

☐ No additional fee is required for this amendment.

☒ Please charge Deposit Account No. 12-1095 in the amount of \$ 234.00.
A duplicate copy of this sheet is enclosed.

☐ A check in the amount of \$ _____ to cover the filing fee is enclosed.

☐ Payment by credit card. Form PTO-2038 is attached.

☒ The Commissioner is hereby authorized to charge and credit Deposit Account No. 12-1095
as described below. A duplicate copy of this sheet is enclosed.

☒ Credit any overpayment.

☒ Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.

Marcus J. Millet
Attorney Reg. No.: 28,241

Dated: March 12, 2003

LERNER, DAVID, LITTENBERG, KRUMHOLZ & MENTLIK, LLP
600 South Avenue West
Westfield, New Jersey 07090
(908) 654-5000

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail, in an envelope addressed to: Commissioner for Patents, Washington, DC 20231, on the date shown below.

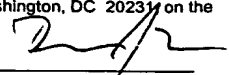
Dated: March 12, 2003

Signature: Marcus J. Millet (Marcus J. Millet)



I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail, in an envelope addressed to: Commissioner for Patents, Washington, DC 20231 on the date shown below.

Dated: March 12, 2003

Signature: 
(Marcus J. Millet)

Docket No.: TESSERA 3.0-109 CIP DIV
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Kim et al

Application No.: 09/776,356

Filed: February 2, 2001

For: STACKED MICROELECTRONIC ASSEMBLY
AND METHOD THEREFOR

:
:
:
:
: Group Art Unit: 2827
:
: Examiner: D. Graybill
:
:
:

Commissioner for Patents
Washington, DC 20231

AMENDMENT

Dear Sir:

In response to the Official Action mailed September 12, 2002, applicant submits the following amendments and remarks.

IN THE CLAIMS

1. (AMENDED) A method of making a stacked microelectronic assembly comprising the steps of:

I. providing a flexible substrate having a plurality of attachment sites, said flexible substrate including a first surface and a second surface and having a plurality of electrically conductive terminals accessible at at least one of said first and second surfaces; test contacts accessible at at least one of said first and second surfaces; and wiring connected to said terminals and test contacts, said wiring including flexible leads extending to said attachment sites;

II. assembling a plurality of microelectronic elements to said attachment sites;

03/20/2003 HLE333 00000023 121095 09776356

02 FC:1202 234.00 CH